TRS3232 3-V to 5.5-V Multichannel RS-232 Line Driver and Receiver With ±15-kV ESD Protection

1 Features

- RS-232 Bus-terminal ESD protection exceeds ±15 kV using human-body model (HBM)
- Meets or exceeds the requirements of TIA/EIA-232-F and ITU V.28 standards
- Operates with 3-V to 5.5-V V_{CC} supply
- Operates up to 250 kbps
- Two drivers and two receivers
- Low supply current: 300-µA typical
- External capacitors: 4 × 0.1 µF
- Accepts 5-V logic input with 3.3-V supply
- Alternative high-speed terminal-compatible devices s (1 Mbps)
  - SN65C3232 (–40°C to 85°C)
  - SN75C3232 (0°C to 70°C)

2 Applications

- Industrial PCs
- Wired networking
- Data cneter and enterprise computing
- Battery-powered systems
- Notebooks
- Laptops
- Palmtop PCs
- Hand-held equipment

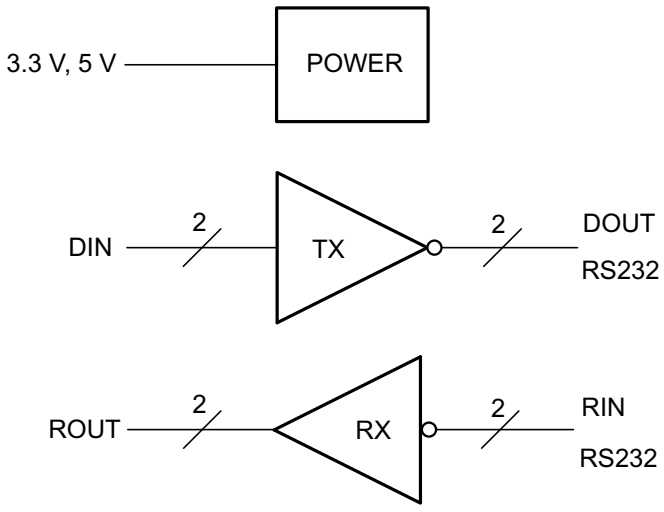
3 Description

The TRS3232 consists of two line drivers, two line receivers, and a dual charge-pump circuit with ±15-kV ESD protection terminal-to-terminal (serial-port connection terminals, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from one 3-V to 5.5-V supply. The devices operate at data-signaling rates up to 250 kbps and a maximum of 30-V/µs driver-output slew rate.

Device Information

PART NUMBER	PACKAGE(1)	BODY SIZE (NOM)
TRS3232	SOIC (16)	9.90 mm × 3.91 mm
	SSOP (16)	6.20 mm × 5.30 mm
	SOIC-Wide (16)	10.30 mm × 7.50 mm
	TSSOP (16)	5.00 mm × 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

Table of Contents

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (July 2015) to Revision B (June 2021)	Page
• Added *Applications:* Industrial PCs, Wired networking, and Data center and enterprise computing	1
• Added additional thermal parameters for all packages in *Thermal Information* table	5

Changes from Revision * (July 2007) to Revision A (June 2015)	Page
• Changed *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Typical Characteristics* section, *Detailed Description* section, *Power Supply Recommendations* and *Layout* sections, *Device and Documentation Support* and *Mechanical, Packaging, and Orderable Information*	1
• Deleted *Ordering Information* table	3

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5 Pin Configuration and Functions

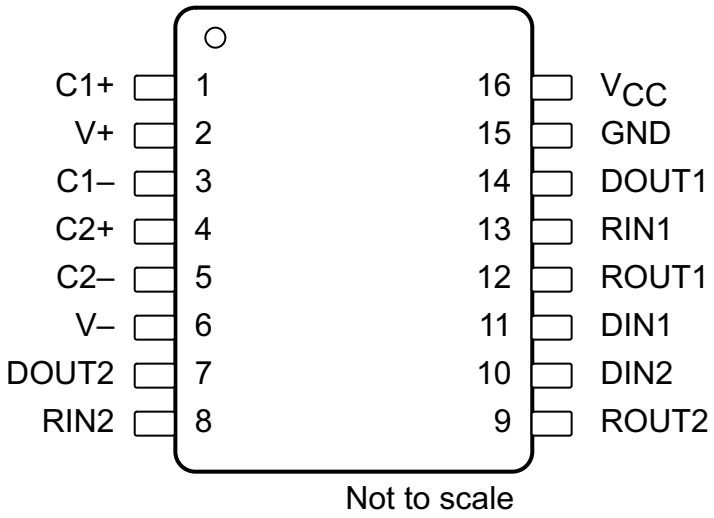

Figure 5-1. D, DB, DW, PW Packages 16-Pin SOIC, SSOP, SOIC (Wide), TSSOP Top View

Table 5-1. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
C1+	1	—	Positive lead of C1 capacitor
C1–	3	—	Negative lead of C1 capacitor
C2+	4	—	Positive lead of C2 capacitor
C2–	5	—	Negative lead of C2 capacitor
DIN1	11	I	Logic data input (from UART)
DIN2	10	I	Logic data input (from UART)
DOUT1	14	O	RS232 line data output (to remote RS232 system)
DOUT2	7	O	RS232 line data output (to remote RS232 system)
GND	15	—	Ground
RIN1	13	I	RS232 line data input (from remote RS232 system)
RIN2	8	I	RS232 line data input (from remote RS232 system)
ROUT1	12	O	Logic data output (to UART)
ROUT2	9	O	Logic data output (to UART)
V+	2	O	Positive charge pump output for storage capacitor only
V–	6	O	Negative charge pump output for storage capacitor only
V_{CC}	16	—	Supply Voltage, Connect to external 3-V to 5.5-V power supply

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage(2)		–0.3	6	V
V_+	Positive output supply voltage(2)		–0.3	7	V
V_-	Negative output supply voltage(2)		–7	0.3	V
$V_+ - V_-$	Supply voltage difference(2)			13	V
V_I	Input voltage	Drivers	–0.3	6	V
		Receivers	–25	25	
V_O	Output voltage	Drivers	–13.2	13.2	V
		Receivers	–0.3	V_{CC} + 0.3	
T_J	Operating virtual junction temperature			150	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) All voltages are with respect to network GND.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 RIN , DOUT, and GND pins (1)	±15000	V
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 All other pins(1)	±3000	
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

(see Figure 9-1)(1)

				MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		V_{CC} = 3.3 V	3	3.3	3.6	V
			V_{CC} = 5 V	4.5	5	5.5	
V_{IH}	Driver high-level input voltage	DIN	V_{CC} = 3.3 V	2			V
			V_{CC} = 5 V	2.4			
V_{IL}	Driver low-level input voltage	DIN				0.8	V
V_I	Driver input voltage	DIN		0		5.5	V
	Receiver input voltage	RIN		–25		25	
T_A	Operating free-air temperature	TRS3232C		0		70	°C
		TRS3232I		–40		85	°C

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

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6.4 Thermal Information

THERMAL METRIC[1]		TRS3232				UNIT
		D (SOIC)	DB (SSOP)	DW (SOIC-wide)	PW (TSSOP)	
		16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	73	82	57	108	°C/W
$R_{\theta JC(top)}$	Junction-to-case (bottom) thermal resistance	38.5	45.8	32.4	39	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	36.3	44.6	31.9	54.4	°C/W
ψ_{JT}	Junction-to-top characterization parameter	8.0	11.1	8.4	3.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	36.0	44	31.5	53.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report (SPRA953).

6.5 Electrical Characteristics—Device

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)[2] (see Figure 9-1)

PARAMETER		TEST CONDITIONS		MIN	TYP[1]	MAX	UNIT
I_{CC}	Supply current	No load,	V_{CC} = 3.3 V to 5 V		0.3	1	mA

(1) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(2) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

6.6 Electrical Characteristics—Driver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)[1] (see Figure 9-1)

PARAMETER		TEST CONDITIONS		MIN	TYP[2]	MAX	UNIT
V_{OH}	High-level output voltage	D_{OUT} at R_L = 3 kΩ to GND,	D_{IN} = GND	5	5.4		V
V_{OL}	Low-level output voltage	D_{OUT} at R_L = 3 kΩ to GND,	D_{IN} = V_{CC}	–5	–5.4		V
I_{IH}	High-level input current	V_I = V_{CC}			±0.01	±1	µA
I_{IL}	Low-level input current	V_I at GND			±0.01	±1	µA
I_{OS} [3]	Short-circuit output current	V_{CC} = 3.6 V	V_O = 0 V		±35	±60	mA
		V_{CC} = 5.5 V	V_O = 0 V				
r_O	Output resistance	V_{CC} = 0 V, V_+ = 0 V, and V_- = 0 V	V_O = ±2 V	300	10M		Ω

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

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6.7 Electrical Characteristics—Receiver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1) (see Figure 9-1)

PARAMETER		TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = –1 mA	V_{CC} – 0.6	V_{CC} – 0.1		V
V_{OL}	Low-level output voltage	I_{OL} = 1.6 mA			0.4	V
V_{IT+}	Positive-going input threshold voltage	V_{CC} = 3.3 V		1.5	2.4	V
		V_{CC} = 5 V		1.8	2.4	
$V_{IT–}$	Negative-going input threshold voltage	V_{CC} = 3.3 V	0.6	1.2		V
		V_{CC} = 5 V	0.8	1.5		
V_{hys}	Input hysteresis (V_{IT+} – $V_{IT–}$)			0.3		V
r_I	Input resistance	V_I = ±3 V to ±25 V	3	5	7	kΩ

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

6.8 Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1) (see Figure 9-1)

PARAMETER		TEST CONDITIONS		MIN	TYP(2)	MAX	UNIT
	Maximum data rate	R_L = 3 kΩ, One D_{OUT} switching,	C_L = 1000 pF See Figure 7-1	150	250		kbps
$t_{sk(p)}$	Driver Pulse skew(3)	R_L = 3 kΩ to 7 kΩ,	C_L = 150 to 2500 pF See Figure 7-2		300		ns
SR(tr)	Driver Slew rate, transition region (see Figure 7-1)	R_L = 3 kΩ to 7 kΩ, V_{CC} = 5 V	C_L = 150 to 1000 pF	6		30	V/µs
			C_L = 150 to 2500 pF	4		30	
t_{PLH}	Receiver Propagation delay time, low- to high-level output	C_L = 150 pF			300		ns
t_{PHL}	Receiver Propagation delay time, high- to low-level output				300		ns
$t_{sk(p)}$	Receiver Pulse skew(1)				300		ns

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

6.9 Typical Characteristics

V_{CC} = 3.3 V

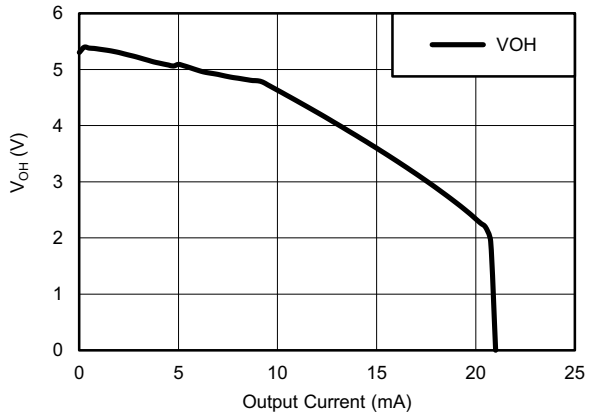

Figure 6-1. DOUT V_{OH} vs Load Current, Both Drivers Loaded

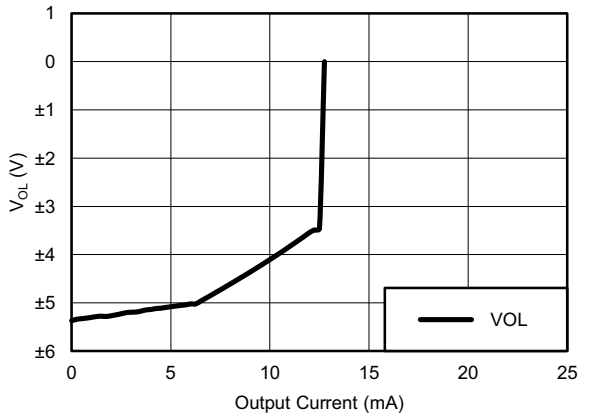

Figure 6-2. DOUT V_{OL} vs Load Current, Both Drivers Loaded

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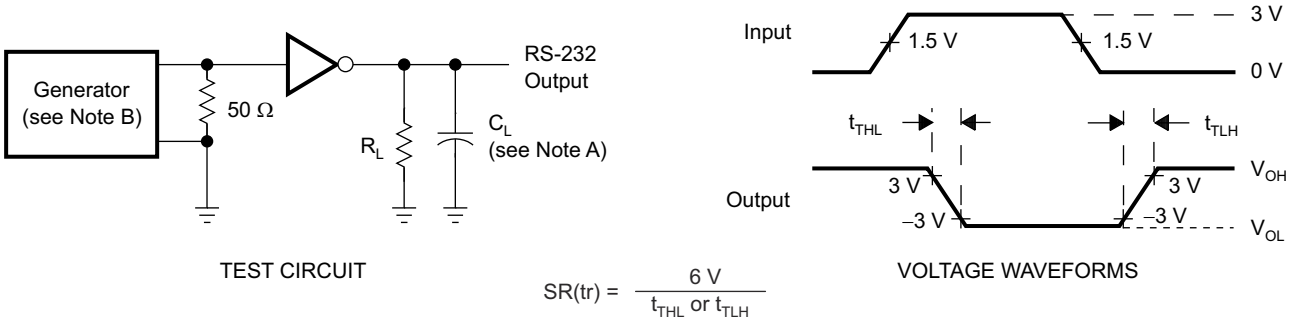
7 Parameter Measurement Information



TEST CIRCUIT

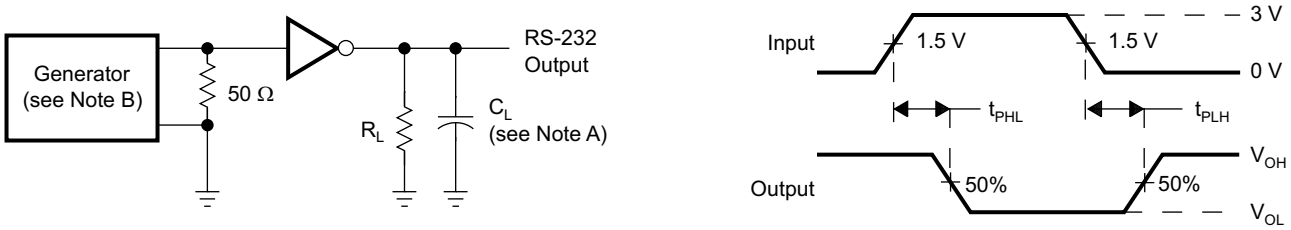
$$SR(tr) = \frac{6\ V}{t_{THL} \text{ or } t_{TLH}}$$

VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbps, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 7-1. Driver Slew Rate



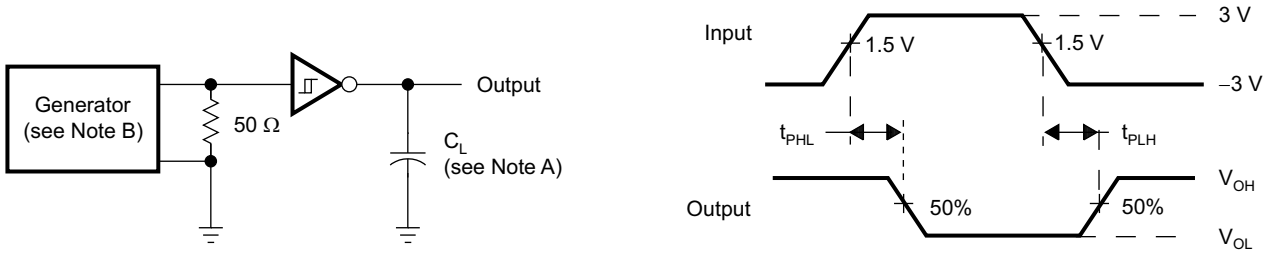
TEST CIRCUIT

VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbps, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 7-2. Driver Pulse Skew



TEST CIRCUIT

VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 7-3. Receiver Propagation Delay Times

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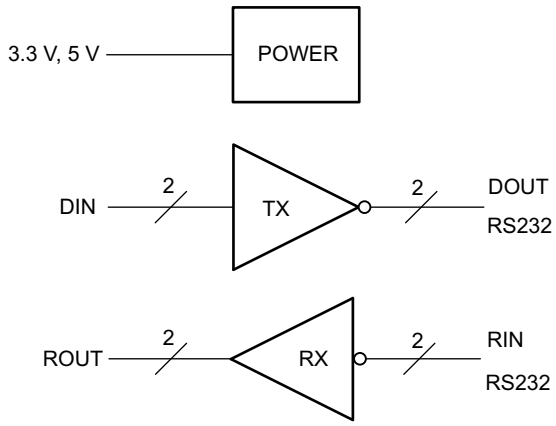
8 Detailed Description

8.1 Overview

The TRS3232 device consists of two line drivers, two line receivers, and a dual charge-pump circuit with ±15-kV ESD protection terminal to terminal (serial-port connection terminals, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from one 3-V to 5.5-V supply. The device operates at data signaling rates up to 250 kbps and a maximum of 30-V/µs driver output slew rate. Outputs are protected against shorts to ground.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Power

The power block increases, inverts, and regulates voltage at V_+ and V_- pins using a charge pump that requires four external capacitors.

8.3.2 RS232 Driver

Two drivers interface the standard logic level to RS232 levels. Both DIN inputs must be valid high or low.

8.3.3 RS232 Receiver

Two receivers interface RS232 levels to standard logic levels. An open input results in a high output on ROUT. Each RIN input includes an internal standard RS232 load.

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8.4 Device Functional Modes

Table 8-1. Each Driver

INPUT DIN(1)	OUTPUT DOUT
L	H
H	L

(1) H = high level, L = low level

Table 8-2. Each Receiver

INPUT RIN(1)	OUTPUT ROUT
L	H
H	L
Open	H

(1) H = high level, L = low level,
Open = input disconnected or connected driver off

8.4.1 V_{CC} Powered by 3 V to 5.5 V

The device is in normal operation.

8.4.2 V_{CC} Unpowered, V_{CC} = 0 V

When the TRS3232 device is unpowered, it can be safely connected to an active remote RS232 device.

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9 Application and Implementation

Note

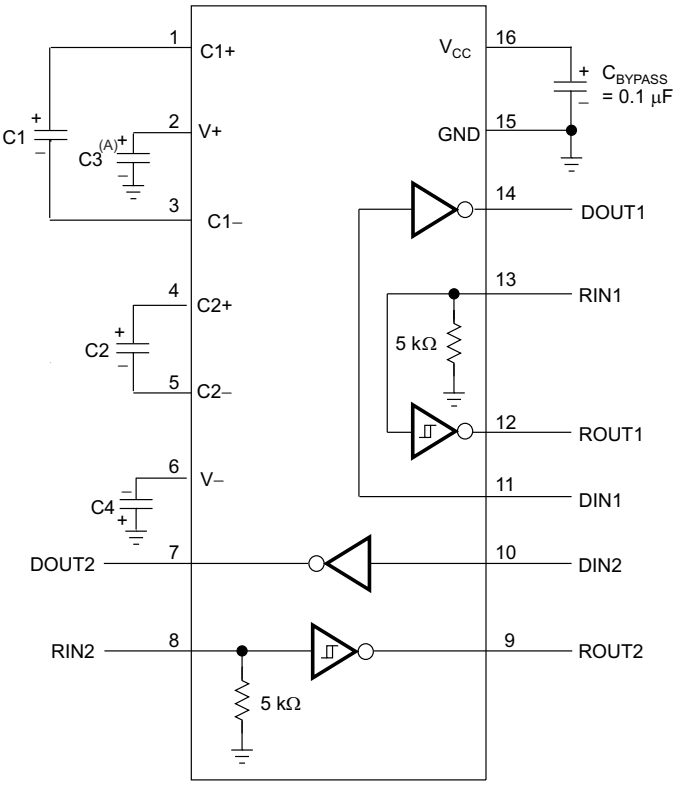
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The TRS3232 is designed to convert single-ended signals into RS232-compatible signals, and vice-versa.

This device can be used in any application where an RS232 line driver or receiver is required. One benefit of this device is its ESD protection, which helps protect other components on the board when the RS232 lines are tied to a physical connector.

9.2 Typical Application



A. C3 can be connected to V_{CC} or GND.
B. Resistor values shown are nominal.
C. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they must be connected as shown.
D. See Table 9-1 for capacitor values.

Figure 9-1. Typical Operating Circuit

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9.2.1 Design Requirements

- Recommended V_{CC} is 3.3 V or 5 V
  - 3 V to 5.5 V is also possible
- Maximum recommended bit rate is 250 kbites

Table 9-1. V_{CC} versus Capacitor Values

V_{CC}	C1	C2, C3, C4
3.3 V ± 0.3 V	0.1 µF	0.1 µF
5 V ± 0.5 V	0.047 µF	0.33 µF
3 V to 5.5 V	0.1 µF	0.47 µF

9.2.2 Detailed Design Procedure

For proper operation, add capacitors as shown in Figure 9-1 and Table 9-1.

All DIN inputs must be connected to valid low or high logic levels.

Select capacitor values based on V_{CC} level for best performance.

9.2.3 Application Curve

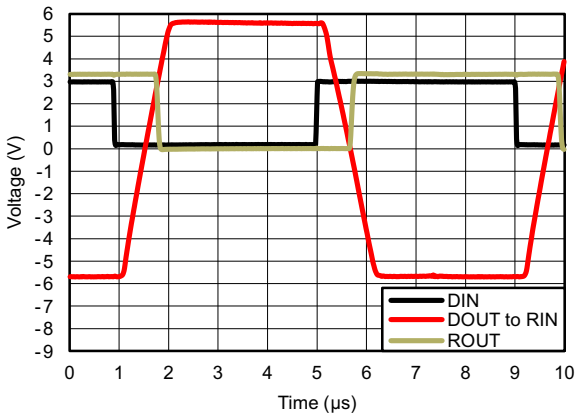

Figure 9-2. 250 kbps Driver to Receiver Loopback Timing Waveform, V_{CC}= 3.3 V

10 Power Supply Recommendations

V_{CC} must be between 3 V and 5.5 V. Charge pump capacitors must be chosen using Table 9-1.

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11 Layout

11.1 Layout Guidelines

Keep the external capacitor traces short. This is more important on C1 and C2 nodes that have the fastest rise and fall times.

11.2 Layout Example

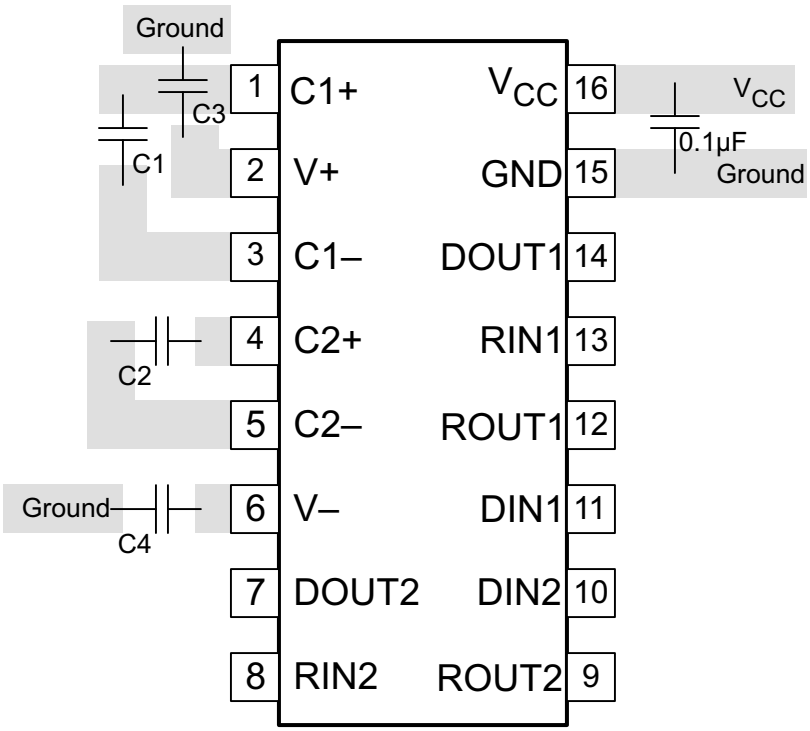

Figure 11-1. Layout Diagram

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12 Device and Documentation Support

12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.5 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TRS3232CDBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	RS32C	Samples
TRS3232CDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS3232C	Samples
TRS3232CDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS3232C	Samples
TRS3232CPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	RS32C	Samples
TRS3232IDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS3232I	Samples
TRS3232IPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RS32I	Samples
TRS3232IPWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RS32I	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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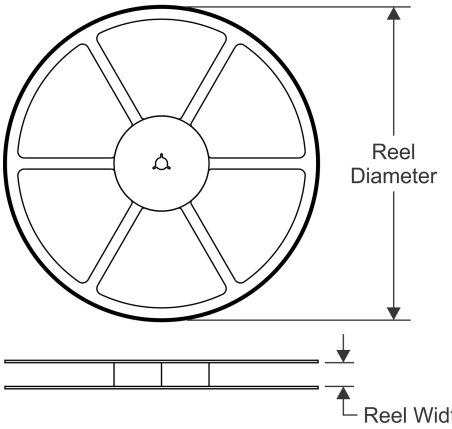
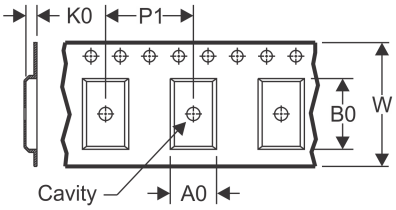
TAPE AND REEL INFORMATION

REEL DIMENSIONS

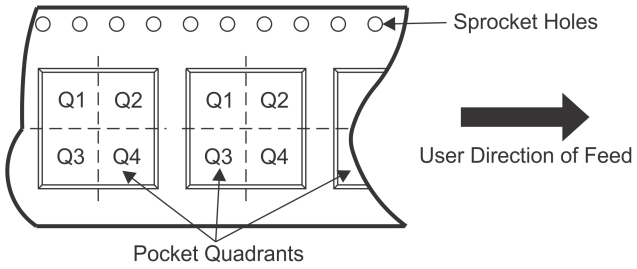


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

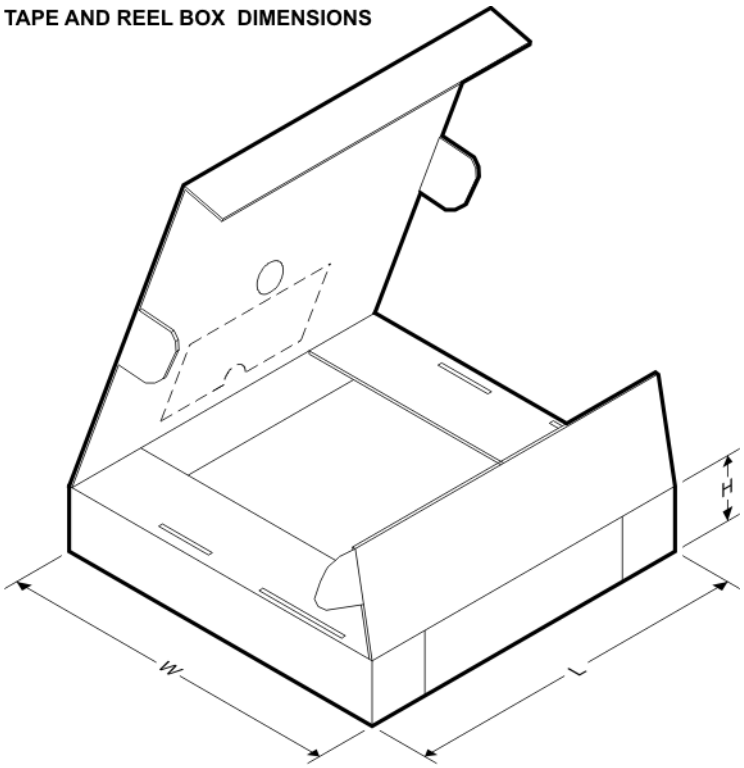
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS3232CDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
TRS3232CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS3232CDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TRS3232IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS3232IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

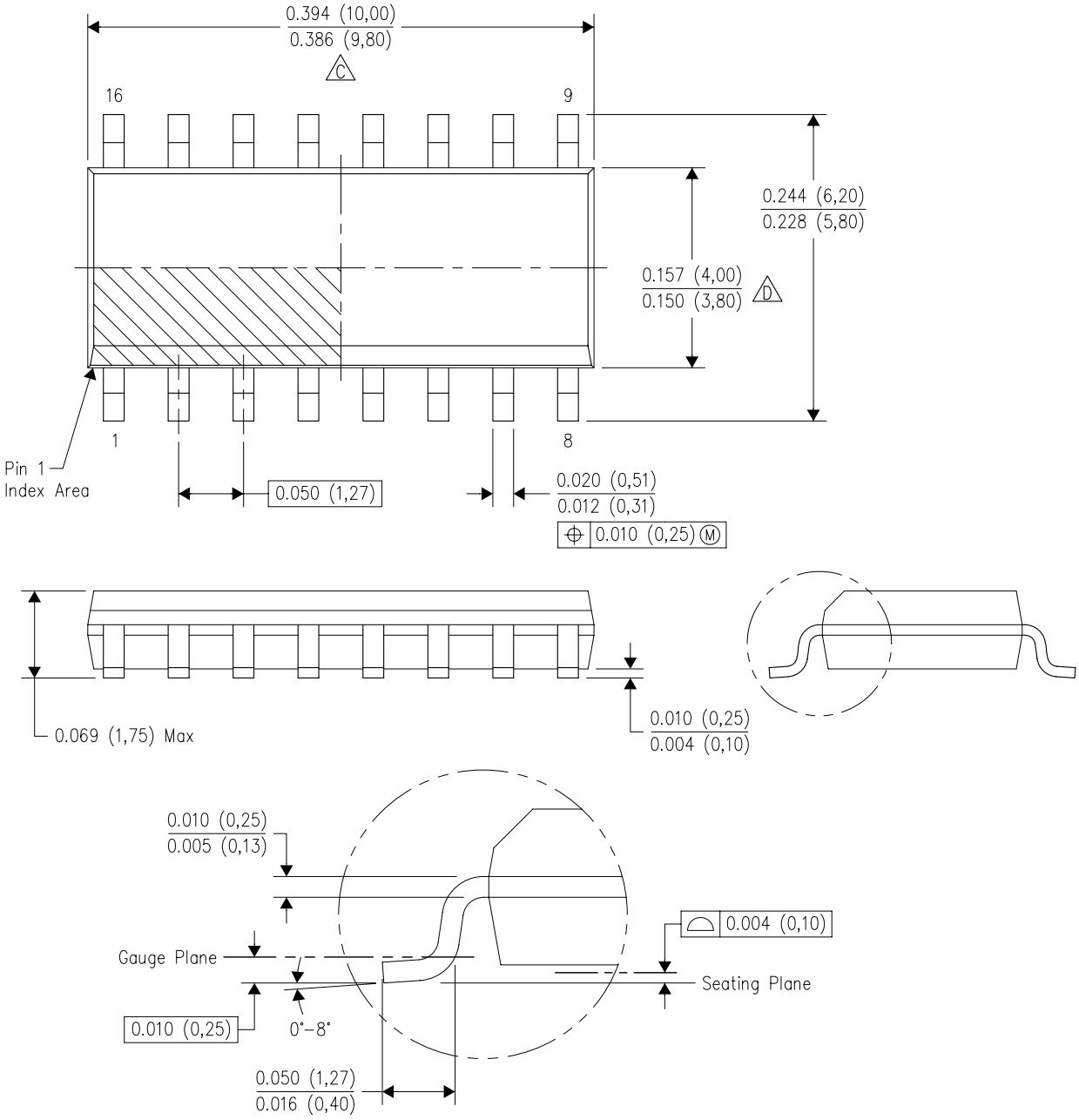
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

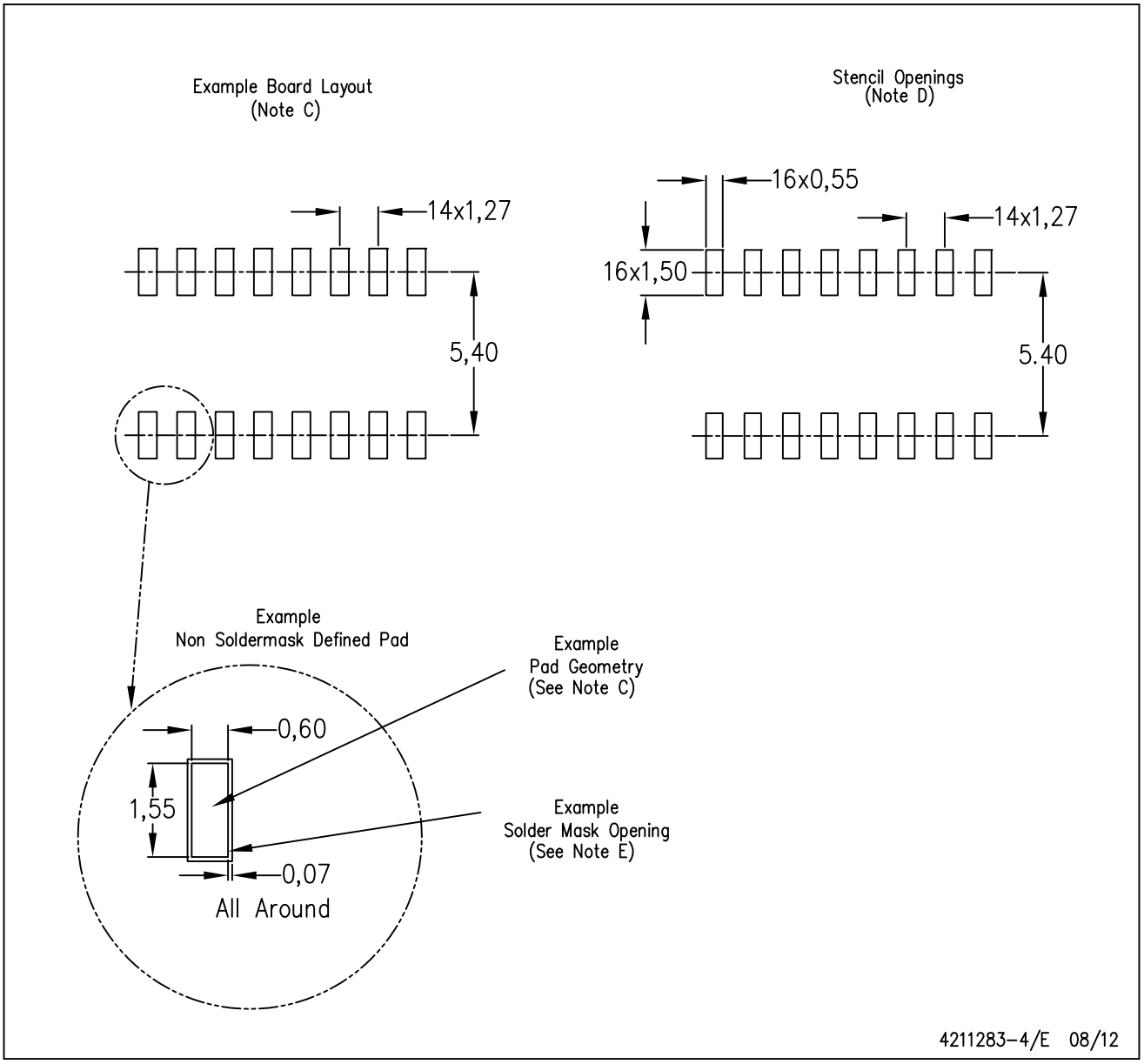
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS3232CDBR	SSOP	DB	16	2000	853.0	449.0	35.0
TRS3232CDR	SOIC	D	16	2500	333.2	345.9	28.6
TRS3232CDWR	SOIC	DW	16	2000	350.0	350.0	43.0
TRS3232IDR	SOIC	D	16	2500	333.2	345.9	28.6
TRS3232IPWR	TSSOP	PW	16	2000	853.0	449.0	35.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



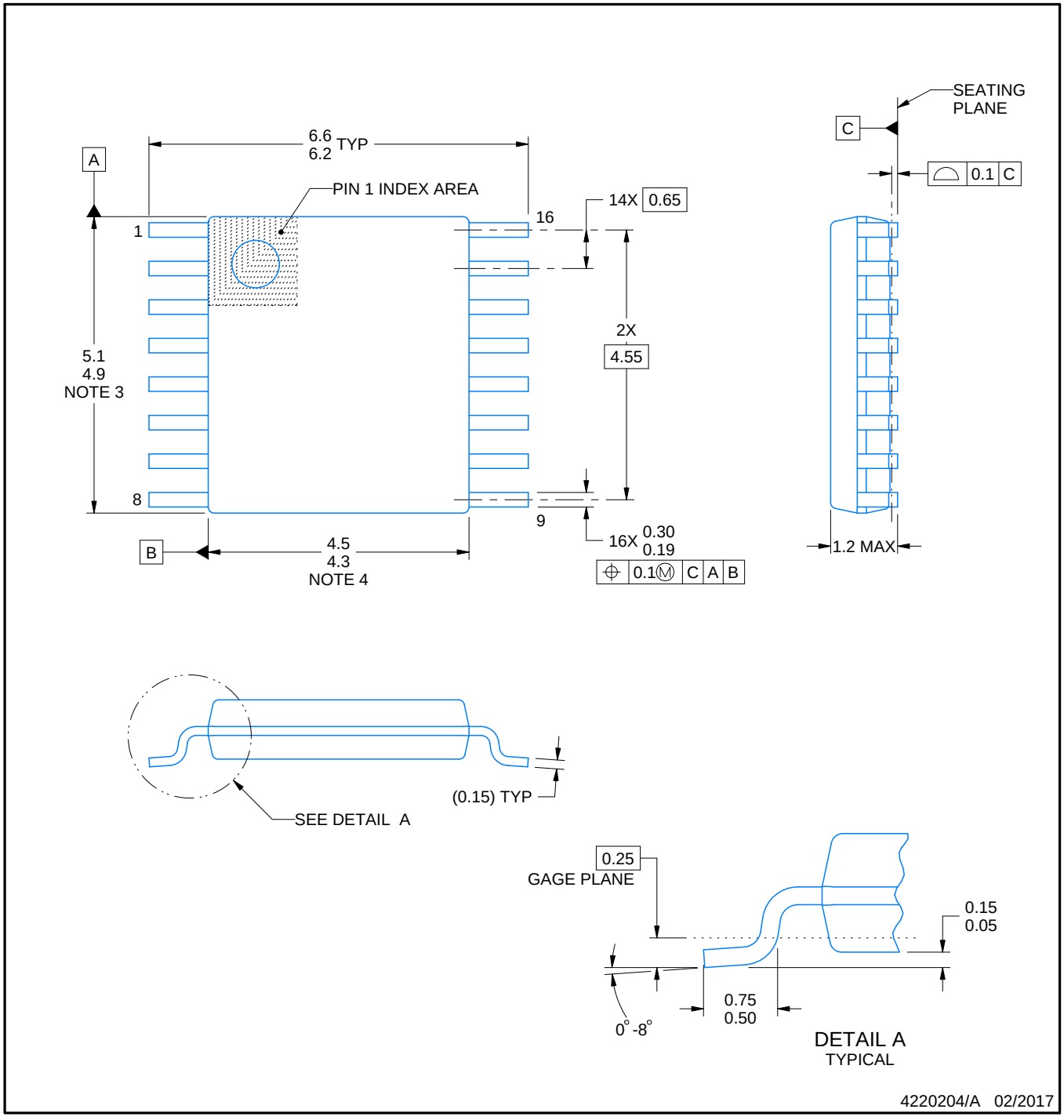
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PACKAGE OUTLINE

PW0016A

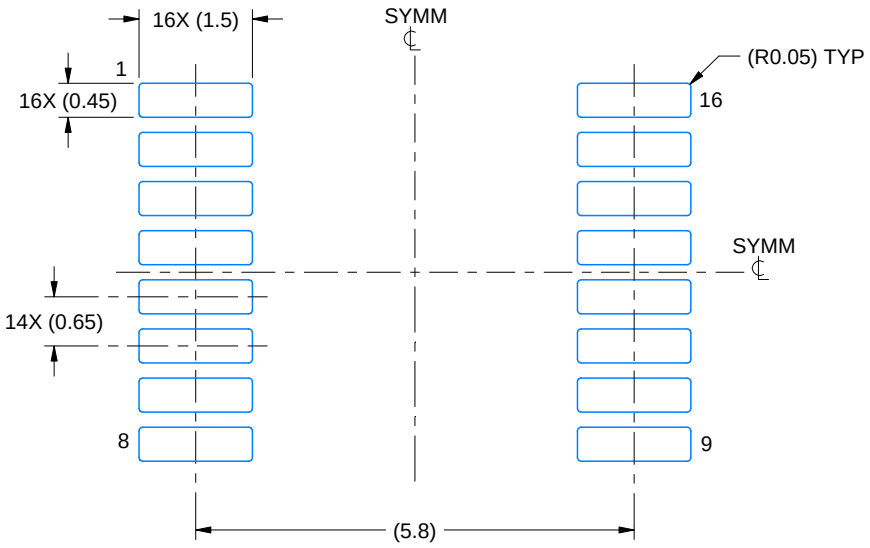
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

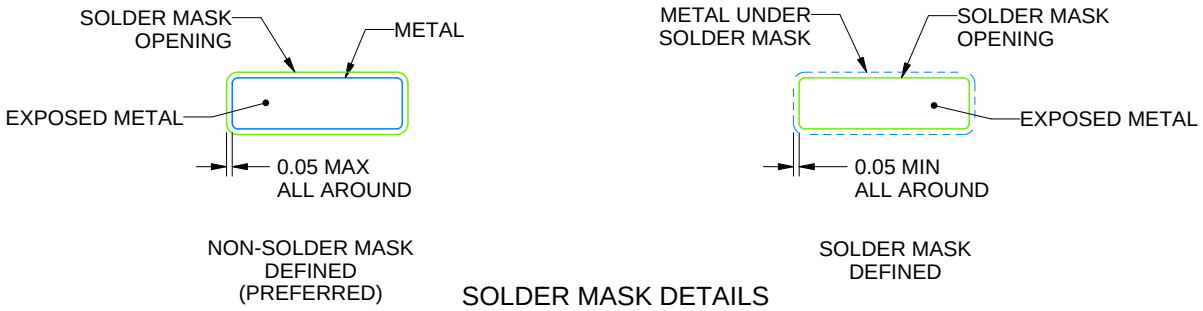


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

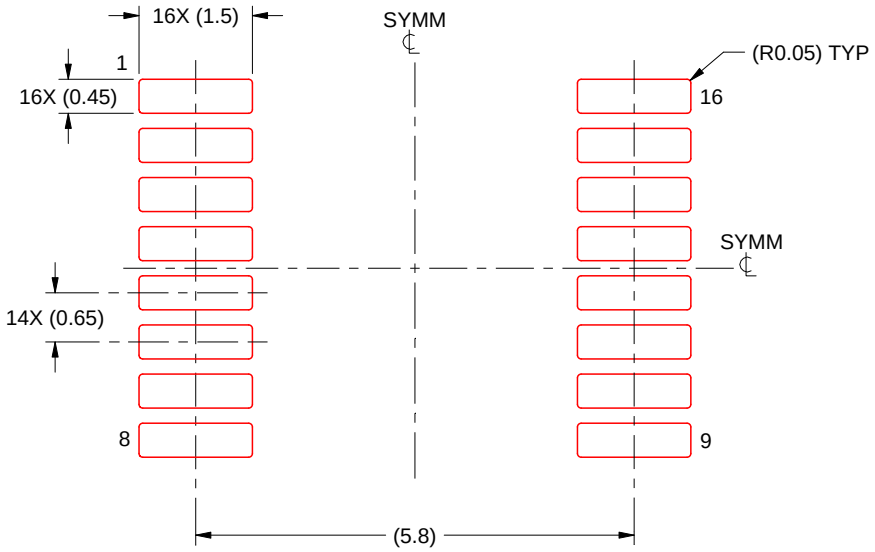


SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

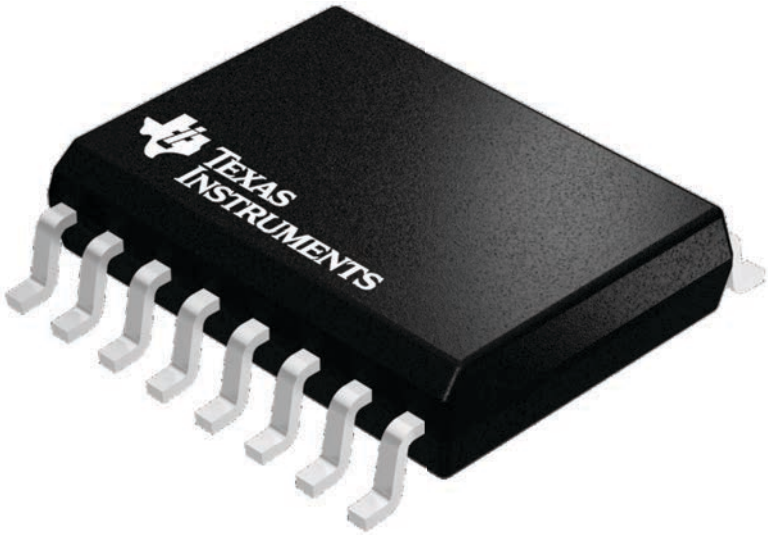
DW 16

SOIC - 2.65 mm max height

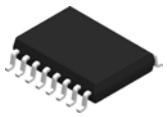
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

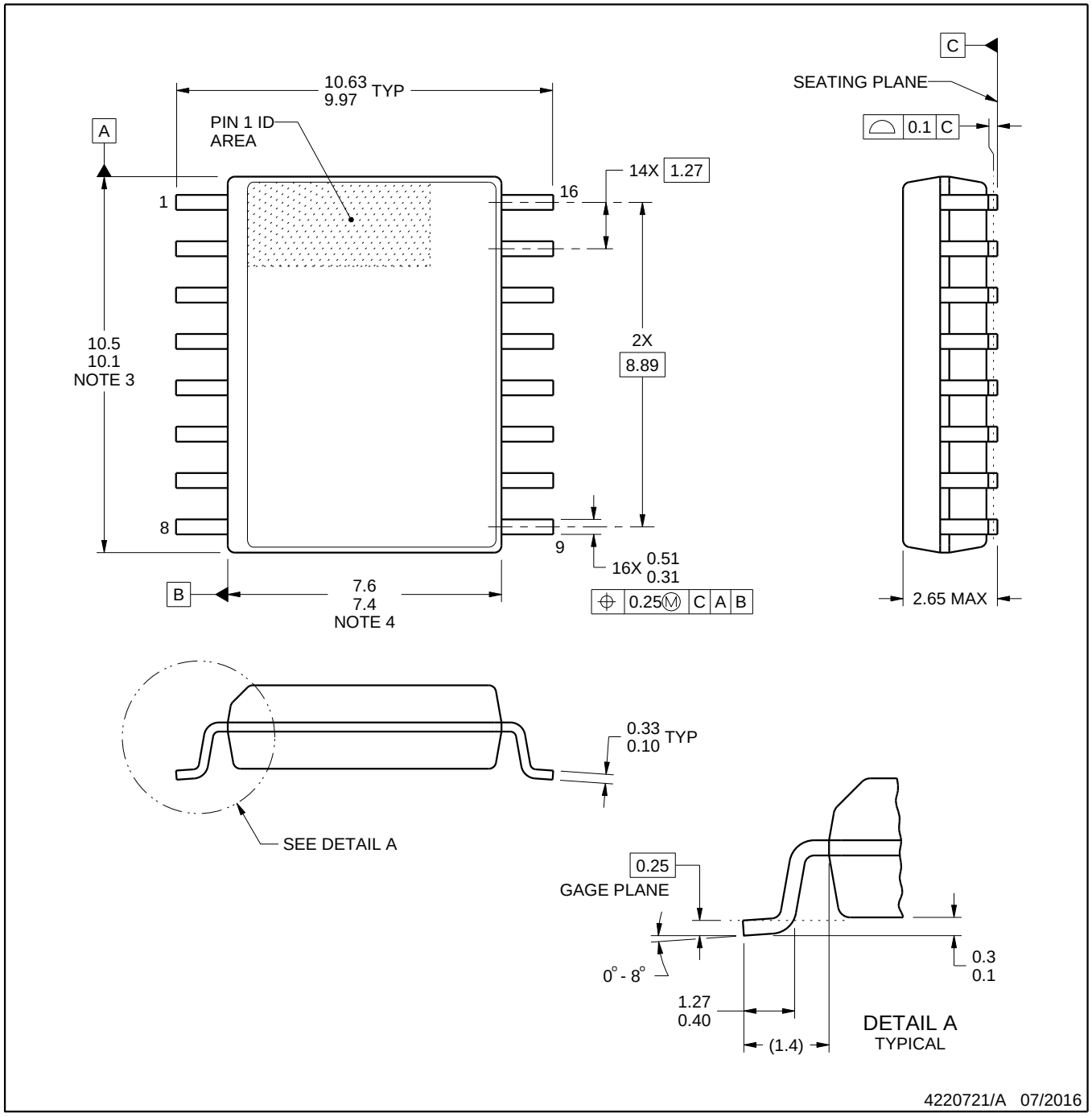


PACKAGE OUTLINE

DW0016A

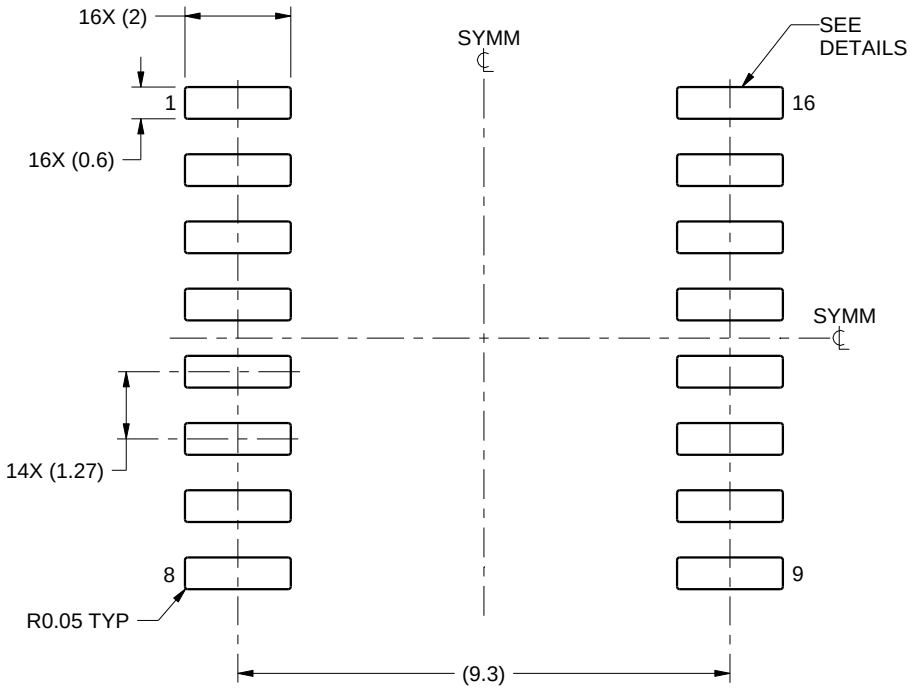
SOIC - 2.65 mm max height

SOIC

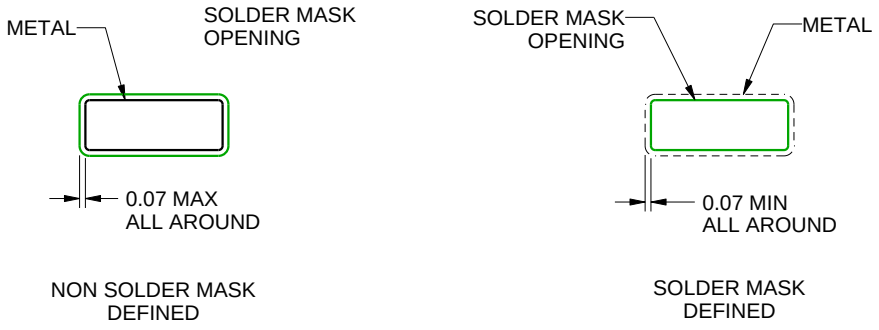


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:7X

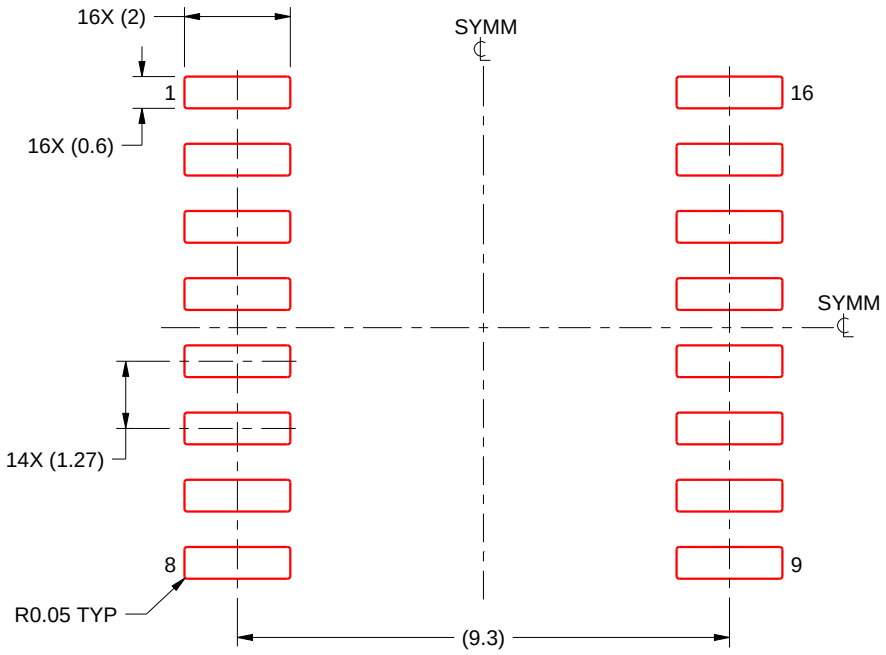


SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

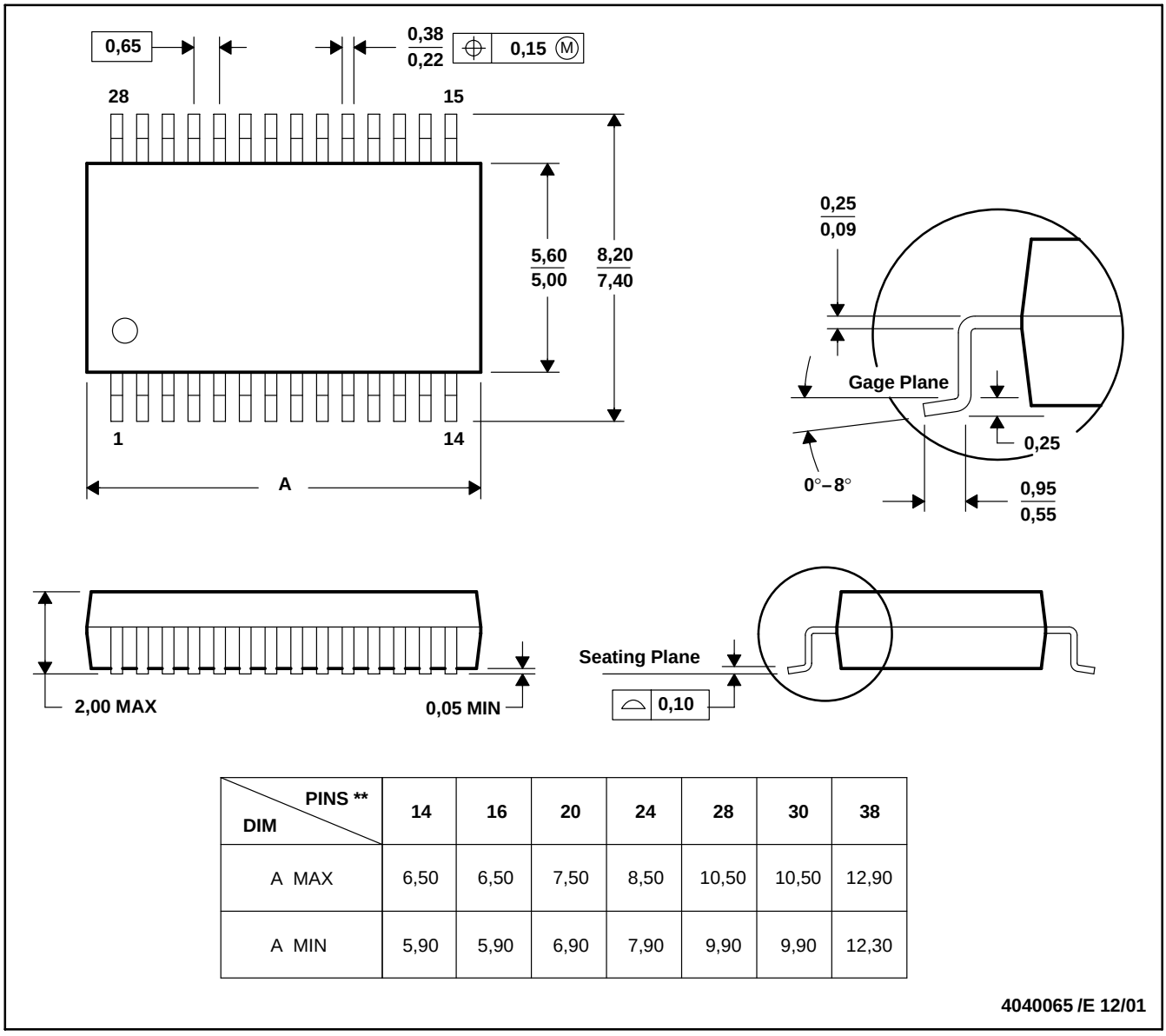
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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